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PATENT ABSTRACTS OF JAPAN

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(71)Applicant : DENSO CORP

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(72)Inventor : YOSHIHARA SHINJI
INOMATA SUMITOMO
ATSUMI KINYA
SAKAI MINEICHI
SHIMOYAMA YASUKI
FUJII TETSUO

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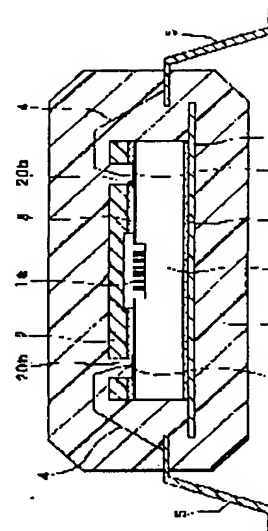
Priority number : 10067276 Priority date : 17.03.1998 Priority country : JP

(54) SEMICONDUCTOR DEVICE AND MANUFACTURE OF IT

(57)Abstract:

PROBLEM TO BE SOLVED: To eliminate the problem caused by intrusion of a cutting water at dicing, related to a semiconductor acceleration sensor comprising a protective cap.

SOLUTION: A heat-resistant resin sheet 2 is used as a protective cap which protects a beam structure body 1a formed at a semiconductor chip 1, while the heat-resistant resin sheet 2 is bonded onto the semiconductor chip 1 with a heat-resistant bonding agent 3. A polyimide base material is used as the heat-resistant resin sheet 2 while a silicon adhesive agent is used as the heat-resistant bonding agent 3. The heat-resistant resin sheet 2 is bonded onto the semiconductor chip 1 with the heat-resistant bonding agent 3 like this so that such a problem as intrusion of cutting water is avoided at dicing cut.



LEGAL STATUS

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